FAIRCHILD

SEMICONDUCTOR®

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NC7WZ17

TinyLogic® UHS Dual Buffer with Schmitt Trigger Inputs

General Description

The NC7WZ17 is a dual buffer with Schmitt trigger inputs from Fairchild's Ultra High Speed Series of TinyLogic® in the SC70 6-lead package. The device is fabricated with advanced CMOS technology to achieve ultra high speed with high output drive while maintaining low static power dissipation over a very broad V_{CC} operating range. The device is specified to operate over the 1.65V to 5.5V V_{CC} range. The inputs and outputs are high impedance when V_{CC} is 0V. Inputs tolerate voltages up to 7V independent of V_{CC} operating voltage. Schmitt trigger inputs typically achieve 1V hysteresis between the positive going and negative going input threshold voltage at 5V V_{CC}.

Features

- Space saving SC70 6-lead package
- Ultra small MicroPak™ Pb-Free leadless package
- Ultra high speed: t_{PD} 3.6ns Typ into 50pF at 5V V_{CC}
- High Output Drive: ±24mA at 3V V_{CC}
- Broad V_{CC} operating range: 1.65V to 5.5V
- Matches the performance of LCX when operated at 3.3V V_{CC}
- Power down high impedance inputs/outputs
- Overvoltage tolerant inputs facilitate 5V to 3V translation
- Patented noise/EMI reduction circuitry implemented

Ordering Information

Order Number	Package Number	Package Code Top Mark	Package Description	Supplied As
NC7WZ17P6X	MAA06A	Z17	6-Lead SC70, EIAJ SC88, 1.25mm Wide	3k Units on Tape and Reel
NC7WZ17P6X_NL[1]	MAA06A	Z17	Pb-Free 6-Lead SC70, EIAJ SC88, 1.25mm Wide	3k Units on Tape and Reel
NC7WZ17L6X	MAC06A	B5	Pb-Free 6-Lead MicroPak, 1.0mm Wide	5k Units on Tape and Reel

Pb-Free package per JEDEC J-STD-020B.

Note:

1. "_NL" indicates Pb-Free product (per JEDEC J-STD-020B). Device is available in Tape and Reel only.
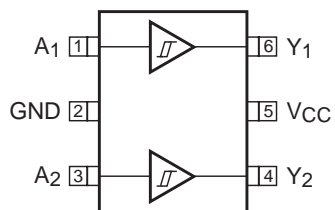
Logic Symbol

IEEE/IEC
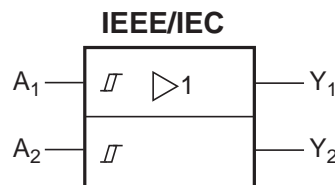
TinyLogic® is a registered trademark of Fairchild Semiconductor Corporation.
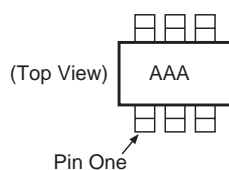MicroPak™ is a trademark of Fairchild Semiconductor Corporation.

Connection Diagrams
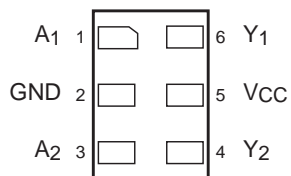
Pin Assignment for SC70

(Top View)

Pin One Orientation Diagram

(Top View) AAA

Pin One

AAA represents Product Code Top Mark – see ordering code

Note: Orientation of Top Mark determines Pin One location. Read the top product code mark left to right, Pin One is the lower left pin (see diagram).

Pad Assignments for MicroPak

(Top Through View)

Pin Descriptions

Pin Name	Description
A_1, A_2	Data Inputs
Y_1, Y_2	Outputs

Function Table

Y = A

Input	Output
A	**Y**
L	L
H	H

H = HIGH Logic Level   L = LOW Logic Level

Absolute Maximum Ratings

The "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be guaranteed.
The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the absolute maximum ratings. The "Recommended Operating Conditions" table will define the conditions for actual device operation.

Symbol	Parameter	Rating
V_{CC}	Supply Voltage	−0.5V to +7V
V_{IN}	DC Input Voltage	−0.5V to +7V
V_{OUT}	DC Output Voltage	−0.5V to +7V
I_{IK}	DC Input Diode Current @ $V_{IN} < -0.5V$	−50mA
I_{OK}	DC Output Diode Current @ $V_{OUT} < -0.5V$	−50mA
I_{OUT}	DC Output Current	±50mA
I_{CC}/I_{GND}	DC V_{CC}/GND Current	±100mA
T_{STG}	Storage Temperature	−65°C to +150°C
T_J	Junction Temperature under Bias	150°C
T_L	Junction Lead Temperature (Soldering, 10 seconds)	260°C
P_D	Power Dissipation @ +85°C	180mW

Recommended Operating Conditions[2]

Symbol	Parameter	Rating
V_{CC}	Supply Voltage Operating	1.65V to 5.5V
V_{CC}	Supply Voltage Data Retention	1.5V to 5.5V
V_{IN}	Input Voltage	0V to 5.5V
V_{OUT}	Output Voltage	0V to V_{CC}
T_A	Operating Temperature	−40°C to +85°C
θ_{JA}	Thermal Resistance	350°C/W

Note:

2. Unused inputs must be held HIGH or LOW. They may not float.

DC Electrical Characteristics

Symbol	Parameter	Conditions		V_{CC} (V)	$T_A =$					Units
					+25°C			-40°C to +85°C		
					Min	Typ	Max	Min	Max	
V_P	Positive Threshold Voltage			1.65	0.6	1.0	1.4	0.6	1.4	V
				1.8	0.7	1.07	1.5	0.7	1.5	
				2.3	1.0	1.38	1.8	1.0	1.8	
				3.0	1.3	1.74	2.2	1.3	2.2	
				4.5	1.9	2.43	3.1	1.9	3.1	
				5.5	2.2	2.88	3.6	2.2	3.6	
V_N	Netative Threshold Voltage			1.65	0.2	0.5	0.8	0.2	0.8	V
				1.8	0.25	0.56	0.9	0.25	0.9	
				2.3	0.40	0.75	1.15	0.40	1.15	
				3.0	0.6	0.98	1.5	0.6	1.5	
				4.5	1.0	1.42	2.0	1.0	2.0	
				5.5	1.2	1.68	2.3	1.2	2.3	
V_H	Hystersis Voltage			1.65	0.1	0.48	0.9	0.1	0.9	V
				1.8	0.15	0.51	1.0	0.15	1.0	
				2.3	0.25	0.62	1.1	0.25	1.1	
				3.0	0.4	0.76	1.2	0.4	1.2	
				4.5	0.6	1.01	1.5	0.6	1.5	
				5.5	0.7	1.20	1.7	0.7	1.7	
V_{OH}	HIGH Level Output Voltage	$V_{IN} = V_{IH}$	$I_{OH} = -100\mu A$	1.65	1.55	1.65		1.55		V
				1.8	1.7	1.8		1.7		
				2.3	2.2	2.3		2.2		
				3.0	2.9	3.0		2.9		
				4.5	4.4	4.5		4.4		
			$I_{OH} = -4mA$	1.65	1.29	1.52		1.29		
			$I_{OH} = -8mA$	2.3	1.9	2.14		1.9		
			$I_{OH} = -16mA$	3.0	2.4	2.75		2.4		
			$I_{OH} = -24mA$	3.0	2.3	2.62		2.3		
			$I_{OH} = -32mA$	4.5	3.8	4.13		3.8		
V_{OL}	LOW Level Output Voltage	$V_{IN} = V_{IL}$	$I_{OL} = 100\mu A$	1.65		0.0	0.1		0.1	V
				1.8		0.0	0.1		0.1	
				2.3		0.0	0.1		0.1	
				3.0		0.0	0.1		0.1	
				4.5		0.0	0.1		0.1	
			$I_{OL} = 4mA$	1.65		0.08	0.24		0.24	
			$I_{OL} = 8mA$	2.3		0.10	0.3		0.3	
			$I_{OL} = 16mA$	3.0		0.16	0.4		0.4	
			$I_{OL} = 24mA$	3.0		0.24	0.55		0.55	
			$I_{OL} = 32mA$	4.5		0.25	0.55		0.55	

DC Electrical Characteristics (Continued)

Symbol	Parameter	Conditions	V_{CC} (V)	$T_A =$ +25°C Min	$T_A =$ +25°C Typ	$T_A =$ +25°C Max	$T_A =$ -40°C to +85°C Min	$T_A =$ -40°C to +85°C Max	Units
I_{IN}	Input Leakage Current	V_{IN} = 5.5V, GND	0 to 5.5			±0.1		±1.0	µA
I_{OFF}	Power Off Leakage Current	V_{IN} or V_{OUT} = 5.5V	0.0			1		10	µA
I_{CC}	Quiescent Supply Current	V_{IN} = 5.5V, GND	1.65 to 5.5			1.0		10	µA

AC Electrical Characteristics

| Symbol | Parameter | Conditions | V_{CC} (V) | $T_A =$ | | | | | Units | Figure Number |
| | | | | +25˚C | | | −40°C to +85°C | | | |
				Min	Typ	Max	Min	Max		
t_{PLH}, t_{PHL}	Propagation Delay	$C_L = 15pF$, $R_L = 1M\Omega$	1.65	2.0	8.3	14.3	2.0	15.8	ns	Figure 1 Figure 3
			1.8	2.0	6.9	11.9	2.0	13.1		
			2.5 ± 0.2	1.5	4.8	8.2	1.5	9.0		
			3.3 ± 0.3	1.0	3.7	5.6	1.0	6.2		
			5.0 ± 0.5	0.8	3.0	4.7	0.8	5.2		
		$C_L = 50pF$, $R_L = 500\Omega$,	3.3 ± 0.3	1.5	4.3	6.6	1.5	7.3	ns	Figure 1 Figure 3
			5.0 ± 0.5	1.0	3.6	5.6	1.0	6.2		
C_{IN}	Input Capacitance		0		2.5				pF	
C_{PD}	Power Dissipation Capacitance	Note 3	3.3		10				pF	Figure 2
			5.0		12					

Notes:

3. C_{PD} is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current consumption (I_{CCD}) at no output loading and operating at 50% duty cycle. (See Figure 2.) C_{PD} is related to I_{CCD} dynamic operating current by the expression:
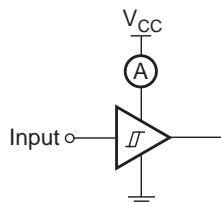
$I_{CCD} = (C_{PD})(V_{CC})(f_{IN}) + (I_{CC}\text{static})$.
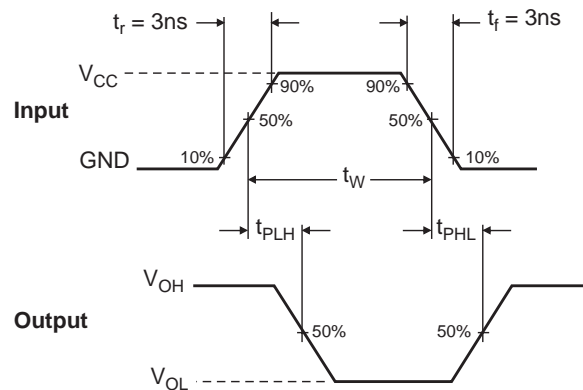
AC Loading and Waveforms
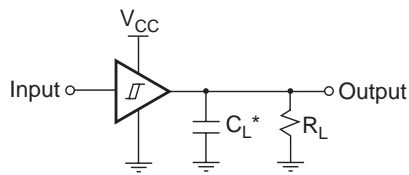
*C_L includes load and stray capacitance.
Input PRR = 1.0MHz; t_W = 500ns

Figure 1. AC Test Circuit

Input = AC Waveform; t_r, t_f = 1.8ns;
PRR = 10MHz; Duty Cycle = 50%
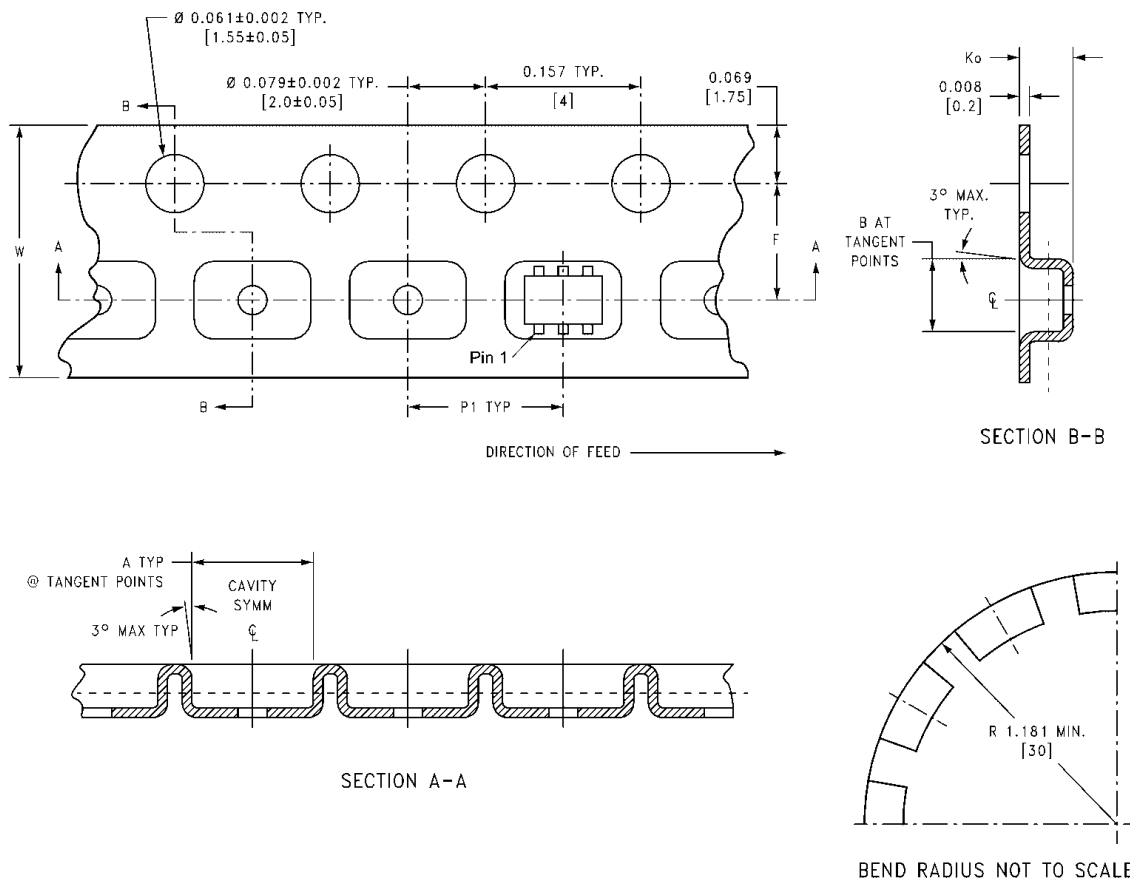
Figure 2. I_{CCD} Test Circuit

Figure 3. AC Waveforms

NC7WZ17 Rev. 1.0.4

Tape and Reel Specification

Tape Format for SC70

Package Designator	Tape Section	Number Cavities	Cavity Status	Cover Tape Status
P6X	Leader (Start End)	125 (typ)	Empty	Sealed
	Carrier	3000	Filled	Sealed
	Trailer (Hub End)	75 (typ)	Empty	Sealed

Tape Dimension inches (millimeters)

Package	Tape Size	Dim A	Dim B	Dim F	Dim K$_O$	Dim P1	Dim W
SC70-6	8mm	0.093 (2.35)	0.096 (2.45)	0.138 ± 0.004 (3.5 ± 0.10)	0.053 ± 0.004 (1.35 ± 0.10)	0.157 (4)	0.315 ± 0.004 (8 ± 0.1)

Tape and Reel Specification (Continued)

Reel Dimension for MicroPak inches (millimeters)

TAPE SLOT

DETAIL X

DETAIL X
SCALE: 3X
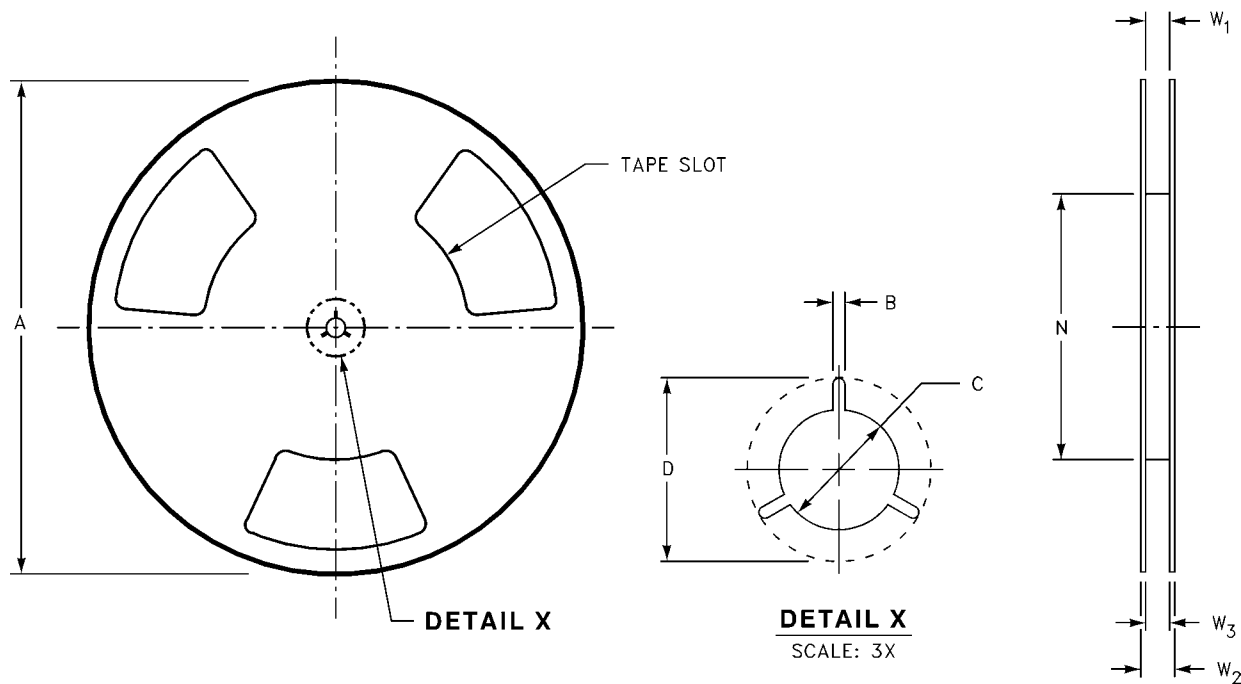
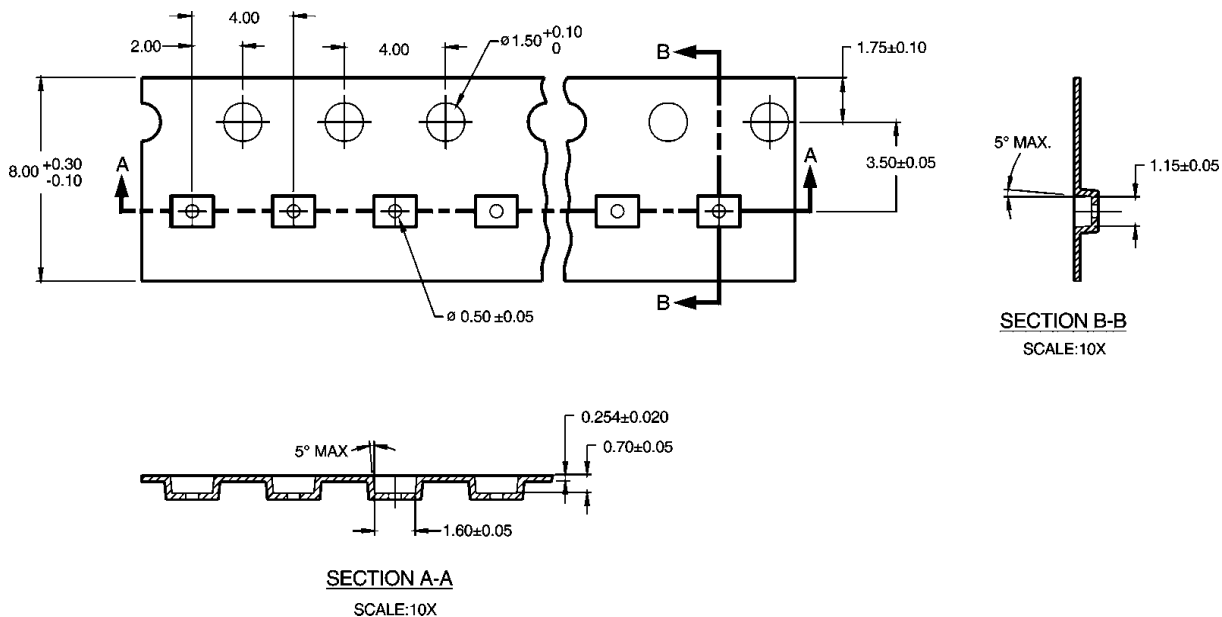| Tape Size	A	B	C	D	N	W1	W2	W3
8 mm	7.0 (177.8)	0.059 (1.50)	0.512 (13.00)	0.795 (20.20)	2.165 (55.00)	0.331 + 0.059/−0.000 (8.40 + 1.50/−0.00)	0.567 (14.40)	W1 + 0.078/−0.039 (W1 + 2.00/−1.00)

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Tape and Reel Specification (Continued)

Tape Format for MicroPak

Package Designator	Tape Section	Number Cavities	Cavity Status	Cover Tape Status
L6X	Leader (Start End)	125 (typ)	Empty	Sealed
	Carrier	3000	Filled	Sealed
	Trailer (Hub End)	75 (typ)	Empty	Sealed

Tape Dimension inches (millimeters)

SECTION B-B
SCALE:10X

SECTION A-A
SCALE:10X

Physical Dimensions inches (millimeters) unless otherwise noted

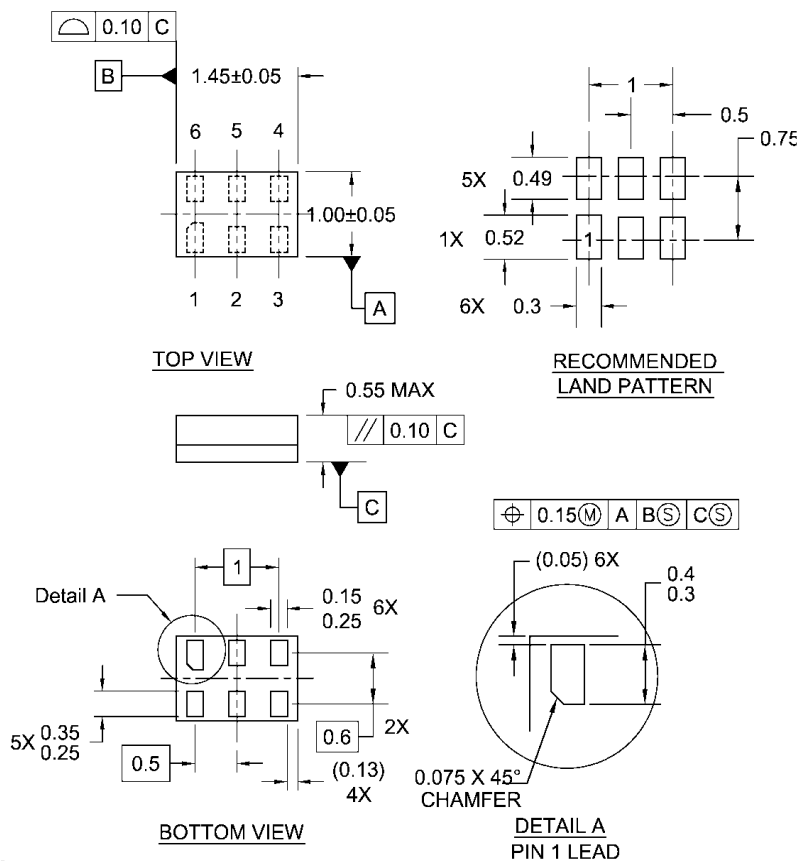LAND PATTERN RECOMMENDATION

SEE DETAIL A

GAGE PLANE

DETAIL A
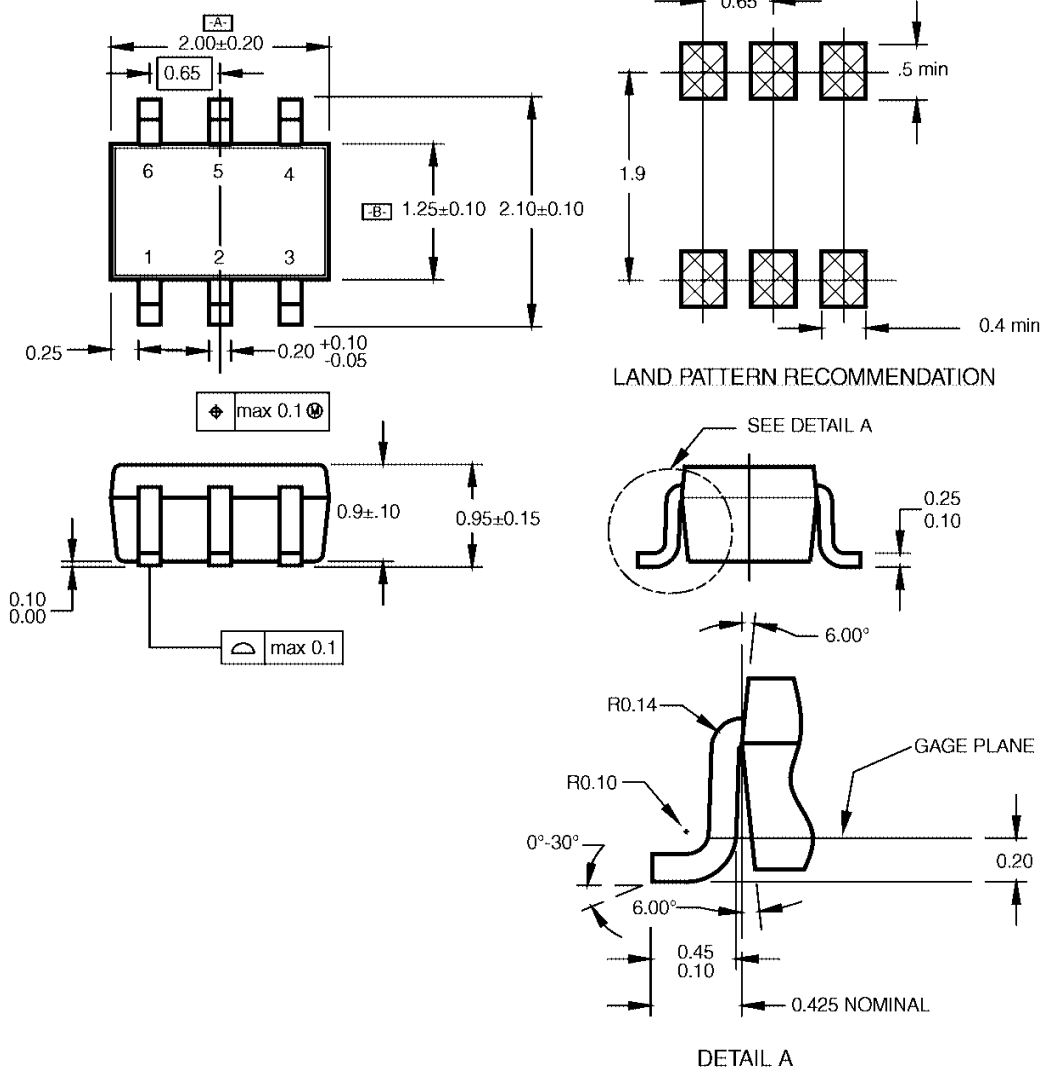
MAA06ARevC

NOTES:

A. CONFORMS TO EIAJ REGISTERED OUTLINE DRAWING SC88.
B. DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH.
C. DIMENSIONS ARE IN MILLIMETERS.

6-Lead SC70, EIAJ SC88, 1.25mm Wide
Package Number MAA06A

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)

⌒ 0.10 C

B 1.45±0.05

6 5 4

1.00±0.05

1 2 3   A

TOP VIEW

1
0.5
0.75

5X 0.49

1X 0.52   1

6X 0.3

RECOMMENDED
LAND PATTERN

0.55 MAX

// 0.10 C

C

⌖ 0.15 Ⓜ A BⓈ CⓈ

(0.05) 6X
0.4
0.3

Detail A

1

0.15 6X
0.25

5X 0.35
0.25

0.5   (0.13) 4X

0.6 2X

0.075 X 45°
CHAMFER

BOTTOM VIEW

DETAIL A
PIN 1 LEAD

Notes:

1. JEDEC PACKAGE REGISTRATION IS ANTICIPATED
2. DIMENSIONS ARE IN MILLIMETERS
3. DRAWING CONFORMS TO ASME Y14.5M-1994

MAC06ARevB

Pb-Free 6-Lead MicroPak, 1.0mm Wide
Package Number MAC06A

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FACT Quiet Series™		OPTOPLANAR™	SMART START™	Wire™
		PACMAN™	SPM™	
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Programmable Active Droop™		PowerEdge™	SuperSOT™-3	

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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
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